HOSTAFORM® XGC25-LW01 XAP®

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Hostaform® XGC25-LW01 XAP® is an injection molding grade reinforced with approximately 25% glass fibers and tribological modification for sliding applications requiring low friction and wear.

Product information

Resin Identification	POM-GF25	ISO 1043
Part Marking Code	>POM-GF25<	ISO 11469

Rheological properties

Moulding shrinkage, parallel	0.8	%	ISO 294-4, 2577
Moulding shrinkage, normal	0.9	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	8100	MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	135	MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	3.5	%	ISO 527-1/-2
Flexural modulus	8000	MPa	ISO 178
Charpy impact strength, 23°C	60	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	12.5	kJ/m²	ISO 179/1eA
Poisson's ratio	0.34[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	160	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	60	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	110	E-6/K	ISO 11359-1/-2

Physical/Other properties

Density	1520	kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

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Characteristics

Processing	Injection Moulding
Special characteristics	Low wear / Low friction, Low emissions

Additional information

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

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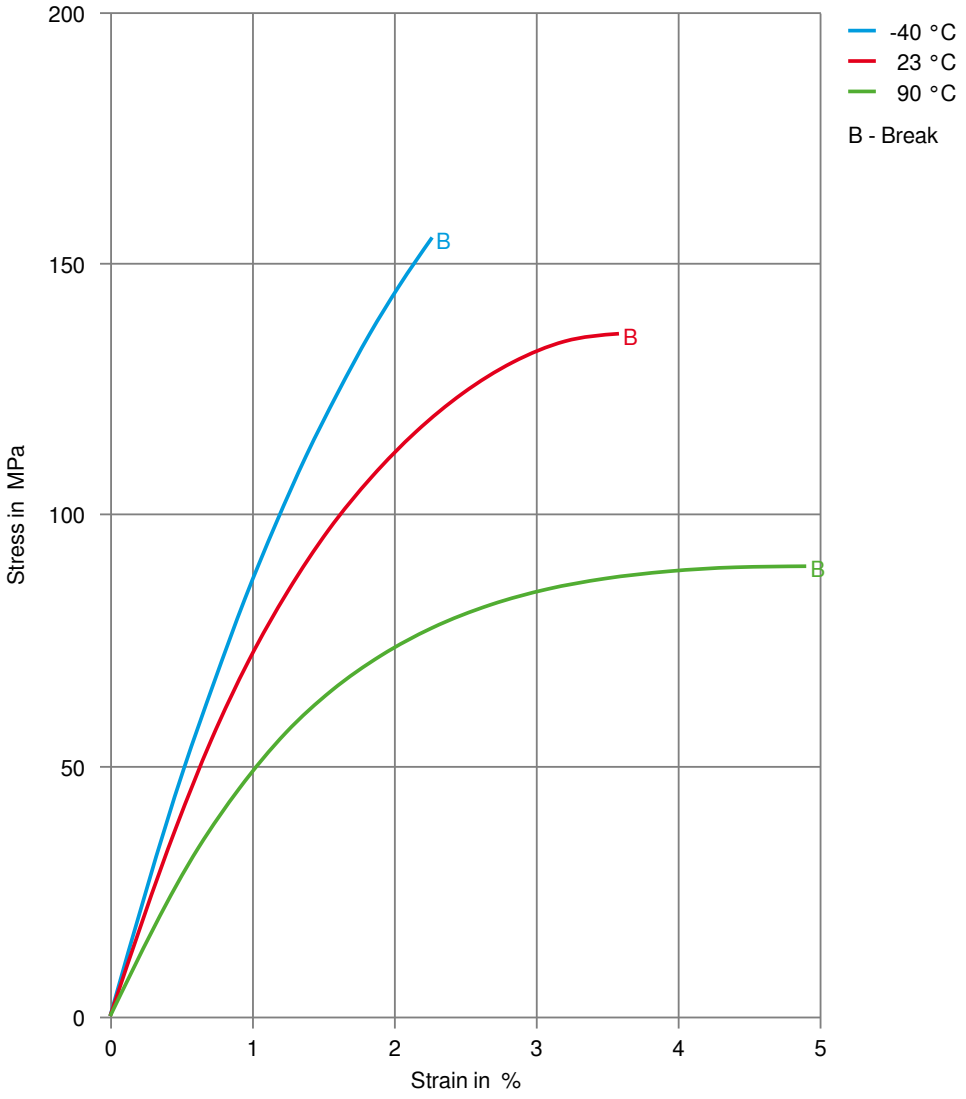
Stress-strain



Revised: 2024-07-08 Source: Celanese Materials Database

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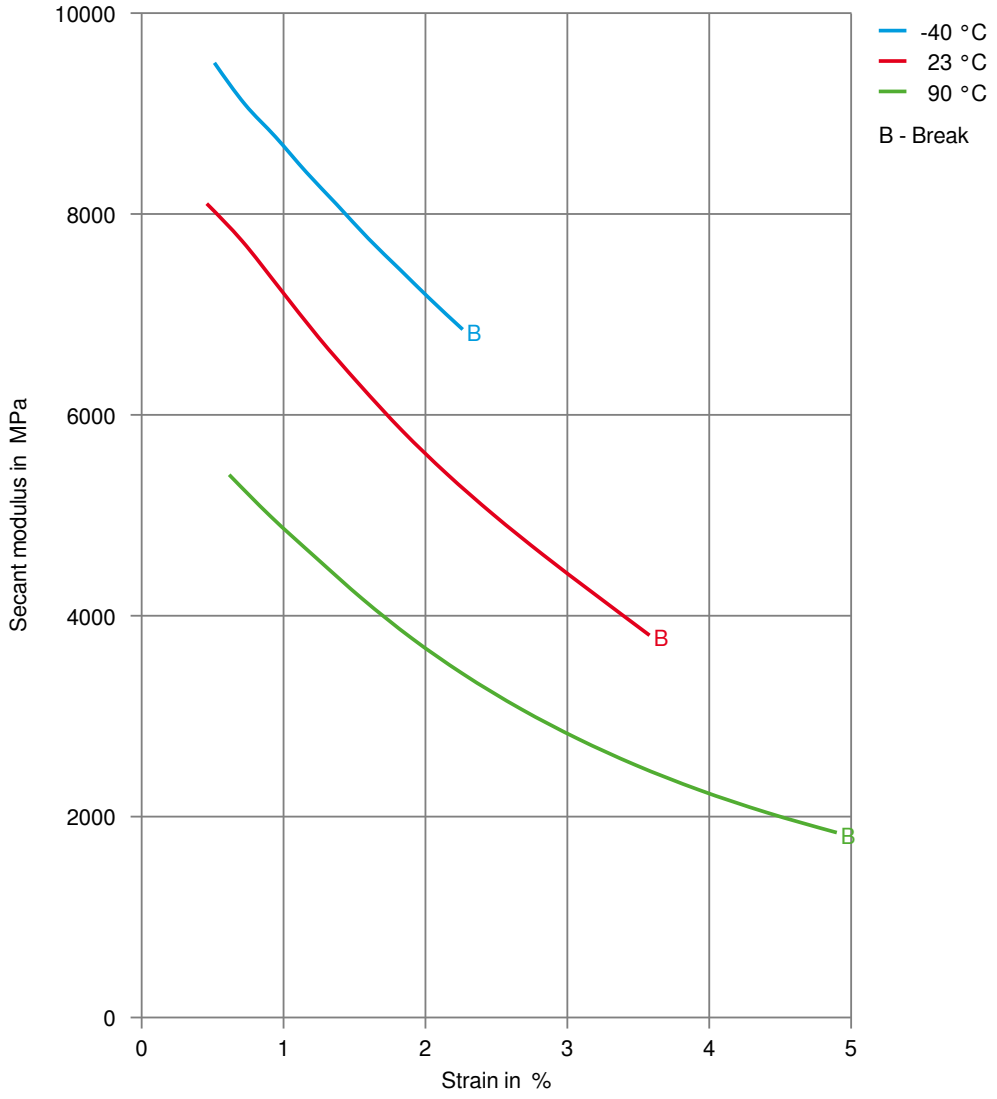
Secant modulus-strain



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